Final Product Change Notification

202110016F01 : SGTL5000 New Part Numbers with Sawn QFN Conversion Due to ASECL Punch QFN Line End-of-Service

Note: This notice is NXP Company Proprietary.

Issue Date: Dec 17, 2021 **Effective date:**Mar 17, 2022

Management summary

Previously NXP Semiconductors issued Advance PCN 202110016A (22-Oct-2021).
Now, Final PCN 202110016F01 is issued due to NXP Semiconductors' assembly subcontractor ASE Chung-Li Taiwan announcement of Punch QFN production line End-of-Service / Decommission, effective 31-Mar-2022, affecting NXP product SGTL5000XNAA3 and SGTL5000XNAA3R2. New SGTL5000 part numbers are created with Sawn QFN conversion for customer supply assurance. Please see details below.

Change Category

☐ Wafer Fab Process
☐ Wafer Fab Materials
☐ Wafer Fab Location
☐ Firmware
☑ Assembly Process
☑ Assembly Materials
☐ Assembly Location
☐ Other
☐ Product Marking
☐ Mechanical Specification
☐ Packing/Shipping/Labeling
☐ Test Process
☐ Test Equipment
☐ Test Location
☐ Design
☐ Errata
☐ Electrical spec./Test coverage

PCN Overview

Description

NXP Semiconductors' assembly subcontractor ASE Chung-Li (ASECL) Taiwan announced the punch QFN production line End-of-Service / Decommission, effective 31-Mar-2022, affecting NXP product

SGTL5000XNAA3 and SGTL5000XNAA3R2. Impacted products will be migrated from Punch QFN to Sawn QFN at the current ASE Chung-Li Taiwan site. Note that ASECL has considerable experience with NXP products in sawn QFN configurations – very low risk change.

New orderable part numbers SGTL5000XNBA3 and SGTL5000XNBA3R2 are offered with sawn QFN package option. Customers are encouraged to migrate to the new part numbers as current part numbers SGTL5000XNAA3 and SGTL5000XNAA3R2 will undergo End-of-Life / Product Discontinuation upon ASECL punch QFN line decommission Mar 2022.

The conversion from Punch QFN to Sawn QFN results in the following change summary:
- Change of lead frame with punch to sawn design
- Change of mold compound material from EME-G700L-Y to EME-G700LA Type L-A Ver.P
- Change of package outline drawing to 98ASA01814D / SOT617-27 from 98ARE10739D / SOT617-15
- Change of exposed pad size (slight increase) to 3.5 x 3.5 mm from 3.3 x 3.3 mm
- No change to lead frame material, thickness, ring type, lead length…
- No change to die attach epoxy material.

Current punch QFN package outline drawing 98ARE10739D / SOT617-15 is attached, and can be found at: https://www.nxp.com.cn/docs/en/package-information/SOT617-15.pdf

New sawn QFN package outline drawing 98ASA01814D / SOT617-27 is attached, and can be found at: https://www.nxp.com.cn/docs/en/package-information/SOT617-27.pdf

The punch to sawn QFN change was successfully qualified adhering to NXP specifications.
Data sheet will be updated to document new orderable part numbers, and sawn QFN package outline drawing change.

Please see the attached files for additional details.

Reason

ASE Chung-Li (ASECL) Taiwan issued an End-of-Service Notice for Punch QFN manufacturing affecting NXP product SGTL5000XNAA3 and SGTL5000XNAA3R2, with effective date 31-Mar-2022. Punch to sawn QFN conversion is required for customer supply assurance.

Identification of Affected Products

Top side marking: New part numbers are created for ASECL sawn QFN package option.

Product Availability

Sample Information

Samples are available upon request
Samples available for SGTL5000XNBA3

Production

Planned first shipment Mar 01, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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Updates to form and fit as described in the accompanying documentation. No impact to function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Old part numbers will undergo End-of-Life / Product Discontinuation upon ASECL Punch QFN line End-of-Service / Decommission 31-Mar-2021

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jan 16, 2022.

Related Notification

Notification	Issue Date	Effective Date	Title
202110016A	Oct 22, 2021		SGTL5000 New Part Numbers with Sawn QFN Conversion Due to ASECL Punch QFN Line End-of-Service

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Xin Dong
Position	Quality Engineer
e-mail address	xin.dong@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands